Ephraim Suhir

List of Publications by Year
in descending order

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191 papers	3,927 citations	201385 27 h-index	168136 53 g-index
194 all docs	194 docs citations	194 times ranked	1234 citing authors

#	Article	IF	Citations
1	Stresses in Bi-Metal Thermostats. Journal of Applied Mechanics, Transactions ASME, 1986, 53, 657-660.	1.1	438
2	New approach to the high quality epitaxial growth of latticeâ€mismatched materials. Applied Physics Letters, 1986, 49, 140-142.	1.5	357
3	Interfacial Stresses in Bimetal Thermostats. Journal of Applied Mechanics, Transactions ASME, 1989, 56, 595-600.	1.1	289
4	An Approximate Analysis of Stresses in Multilayered Elastic Thin Films. Journal of Applied Mechanics, Transactions ASME, 1988, 55, 143-148.	1.1	192
5	Thermal properties of carbon nanotube array used for integrated circuit cooling. Journal of Applied Physics, 2006, 100, 074302.	1.1	95
6	Structural Analysis in Microelectronic and Fiber-Optic Systems. , 1991, , .		95
7	Applied Probability for Engineers and Scientists. Journal of Electronic Packaging, Transactions of the ASME, 1997, 119, 213-214.	1.2	93
8	Analysis of interfacial thermal stresses in a trimaterial assembly. Journal of Applied Physics, 2001, 89, 3685-3694.	1.1	72
9	Mechanical approach to the evaluation of the low temperature threshold of added transmission losses in single-coated optical fibers. Journal of Lightwave Technology, 1990, 8, 863-868.	2.7	69
10	Effect of initial curvature on low temperature microbending in optical fibers. Journal of Lightwave Technology, 1988, 6, 1321-1327.	2.7	53
11	Thermally induced stresses in an optical glass fiber soldered into a ferrule. Journal of Lightwave Technology, 1994, 12, 1766-1770.	2.7	51
12	Predictive Analytical Thermal Stress Modeling in Electronics and Photonics. Applied Mechanics Reviews, 2009, 62, .	4.5	51
13	Predicted thermal stresses in a bimaterial assembly adhesively bonded at the ends. Journal of Applied Physics, 2001, 89, 120-129.	1.1	50
14	Accelerated Life Testing (ALT) in Microelectronics and Photonics: Its Role, Attributes, Challenges, Pitfalls, and Interaction With Qualification Tests1. Journal of Electronic Packaging, Transactions of the ASME, 2002, 124, 281-291.	1.2	49
15	Thermal stress in a polymer-coated optical glass fiber with a low-modulus coating at the ends. Journal of Materials Research, 2001, 16, 2996-3004.	1.2	44
16	Adhesively bonded assemblies with identical nondeformable adherends and â€˜piecewise continuousâ€™ adhesive layer: predicted thermal stresses in the adhesive. International Journal of Solids and Structures, 2000, 37, 2229-2252.	1.3	43
17	Microelectronics and photonics â€” the future. Microelectronics Journal, 2000, 31, 839-851.	1.1	43
18	Could electronics reliability be predicted, quantified and assured?. Microelectronics Reliability, 2013, 53, 925-936.	0.9	40

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19	Stresses in Adhesively Bonded Bi-Material Assemblies Used in Electronic Packaging. Materials Research Society Symposia Proceedings, 1986, 72, 133.	0.1	38
20	Predicted thermally induced stresses in, and the bow of, a circular substrate/thin-film structure. Journal of Applied Physics, 2000, 88, 2363-2370.	1.1	38
21	Assembly Bonded at the Ends: Could Thinner and Longer Legs Result in a Lower Thermal Stress in a Thermoelectric Module Design?. Journal of Applied Mechanics, Transactions ASME, 2012, 79, .	1.1	38
22	Spring constant in the buckling of dual-coated optical fibers. Journal of Lightwave Technology, 1988, 6, 1240-1244.	2.7	36
23	BOLTZMANNâ€“ARRHENIUSâ€“ZHURKOV (BAZ) MODEL IN PHYSICS-OF-MATERIALS PROBLEMS. Modern Physics Letters B, 2013, 27, 1330009.	1.0	36
24	Analytical Modeling in Electronic Packaging Structures: Its Merits, Shortcomings and Interaction With Experimental and Numerical Techniques. Journal of Electronic Packaging, Transactions of the ASME, 1989, 111, 157-161.	1.2	35
25	Axisymmetric Elastic Deformations of a Finite Circular Cylinder With Application to Low Temperature Strains and Stresses in Solder Joints. Journal of Applied Mechanics, Transactions ASME, 1989, 56, 328-333.	1.1	31
26	Interfacial thermal stresses in a bi-material assembly with a low-yield-stress bonding layer. Modelling and Simulation in Materials Science and Engineering, 2006, 14, 1421-1432.	0.8	31
27	Manned missions to Mars: Minimizing risks of failure. Acta Astronautica, 2014, 93, 148-161.	1.7	29
28	Response of a Flexible Printed Circuit Board to Periodic Shock Loads Applied to its Support Contour. Journal of Applied Mechanics, Transactions ASME, 1992, 59, S253-S259.	1.1	28
29	Nonlinear dynamic response of a flexible thin plate to constant acceleration applied to its support contour, with application to printed circuit boards, used in avionic packaging. International Journal of Solids and Structures, 1992, 29, 41-55.	1.3	28
30	Predicted Thermal Mismatch Stresses in a Cylindrical Bi-material Assembly Adhesively Bonded at Its Ends. Journal of Applied Mechanics, Transactions ASME, 1997, 64, 15-22.	1.1	28
31	The Future of Microelectronics and Photonics and the Role of Mechanics and Materials. Journal of Electronic Packaging, Transactions of the ASME, 1998, 120, 1-11.	1.2	28
32	Human in the Loop: Predicted Likelihood of Vehicular Mission Success and Safety. Journal of Aircraft, 2012, 49, 29-36.	1.7	28
33	Mechanical Behavior of Flip-Chip Encapsulants. Journal of Electronic Packaging, Transactions of the ASME, 1990, 112, 327-332.	1.2	27
34	Thermal Stress Failures in Electronics and Photonics: Physics, Modeling, Prevention. Journal of Thermal Stresses, 2013, 36, 537-563.	1.1	26
35	Could shock tests adequately mimic drop test conditions?. , 0, , .		25
36	Approximate Evaluation of the Elastic Thermal Stresses in a Thin Film Fabricated on a Very Thick Circular Substrate. Journal of Electronic Packaging, Transactions of the ASME, 1994, 116, 171-176.	1.2	24

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37	Failure criterion for moisture-sensitive plastic packages of integrated circuit (IC) devices: Application of von KÃ¡rmÃ¡n's equations with consideration of thermoelastic strains. International Journal of Solids and Structures, 1997, 34, 2991-3019.	1.3	24
38	Bimaterial assembly with a low modulus bonding layer at the ends. Journal of Applied Physics, 2003, 93, 3657-3661.	1.1	24
39	Minimizing thermally induced interfacial shearing stress in a thermoelectric module with low fractional area coverage. Microelectronics Journal, 2014, 45, 547-553.	1.1	24
40	Predicted stresses and strains in fused biconical taper couplers subjected to tension. Applied Optics, 1993, 32, 3237.	2.1	21
41	Approximate evaluation of the interfacial shearing stress in cylindrical double lap shear joints with application to dual-coated optical fibers. International Journal of Solids and Structures, 1994, 31, 3261-3283.	1.3	21
42	Optical fiber interconnect with the ends offset and axial loading: What could be done to reduce the tensile stress in the fiber?. Journal of Applied Physics, 2000, 88, 3865.	1.1	21
43	Predicted reliability of aerospace electronics: Application of two advanced probabilistic concepts. , 2013, , .		21
44	Could thermal stresses in a BGA/CGA-system be evaluated from a model intended for a homogeneously bonded assembly?. Journal of Materials Science: Materials in Electronics, 2016, 27, 570-579.	1.1	20
45	Buffering effect of fiber coating and its influence on the proof test load in optical fibers. Applied Optics, 1990, 29, 2682.	2.1	19
46	Predicted Fundamental Vibration Frequency of a Heavy Electronic Component Mounted on a Printed Circuit Board. Journal of Electronic Packaging, Transactions of the ASME, 2000, 122, 3-5.	1.2	19
47	Nonlinear dynamic response of a â€˜flexible-and-heavyâ€™ printed circuit board (PCB) to an impact load applied to its support contour. Journal Physics D: Applied Physics, 2009, 42, 045506.	1.3	19
48	Probabilistic design-for-reliability concept and novel approach to qualification testing of aerospace electronic products. , 2012, , .		19
49	'Miracle-on-the-Hudson': quantitative aftermath. International Journal of Human Factors Modelling and Simulation, 2013, 4, 35.	0.1	19
50	Analysis of a pre-stressed bi-material accelerated-life-test (ALT) specimen. ZAMM Zeitschrift Fur Angewandte Mathematik Und Mechanik, 2011, 91, 371-385.	0.9	18
51	Solder-Glass Attachment in Cerdip/Cerquad Packages: Thermally Induced Stresses and Mechanical Reliability. Journal of Electronic Packaging, Transactions of the ASME, 1990, 112, 204-209.	1.2	17
52	Adhesively bonded assemblies with identical nondeformable adherends: modeling of the induced thermal stresses in the adhesive layer. Composite Interfaces, 1998, 6, 135-154.	1.3	17
53	Adhesively Bonded Assemblies with Identical Nondeformable Adherends and Nonhomogeneous Adhesive Layer: Predicted Thermal Stresses in the Adhesive. Journal of Reinforced Plastics and Composites, 1998, 17, 1588-1606.	1.6	17
54	Thermal stress in a bi-material assembly with a â€˜piecewise-continuousâ€™ bonding layer: theorem of three axial forces. Journal Physics D: Applied Physics, 2009, 42, 045507.	1.3	17

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55	Thermal stress in through-silicon-vias: Theory-of-elasticity approach. Microelectronics Reliability, 2014, 54, 972-977.	0.9	17
56	Analysis of a short beam with application to solder joints: could larger stand-off heights relieve stress?. EPJ Applied Physics, 2015, 71, 31301.	0.3	17
57	Bending Stress in an Optical Fiber Interconnect Experiencing Significant Ends Off-Set. Materials Research Society Symposia Proceedings, 1998, 531, 209.	0.1	16
58	Predicted Thermal Stress in a Multileg Thermoelectric Module (TEM) Design. Journal of Applied Mechanics, Transactions ASME, 2013, 80, .	1.1	16
59	On a Paradoxical Situation Related to Bonded Joints: Could Stiffer Mid-Portions of a Compliant Attachment Result in Lower Thermal Stress?. Journal of Solid Mechanics and Materials Engineering, 2009, 3, 990-997.	0.5	15
60	Helicopter Landing Ship: Undercarriage Strength and the Role of the Human Factor. Journal of Offshore Mechanics and Arctic Engineering, 2010, 132, .	0.6	15
61	Two Men in a Cockpit: Casualty Likelihood if One Pilot Becomes Incapacitated. Journal of Aircraft, 2011, 48, 1309-1314.	1.7	15
62	Three-step concept (TSC) in modeling microelectronics reliability (MR): Boltzmannâ€“Arrheniusâ€“Zhurkov (BAZ) probabilistic physics-of-failure equation sandwiched between two statistical models. Microelectronics Reliability, 2014, 54, 2594-2603.	0.9	15
63	HALT, FOAT and their role in making a viable device into a reliable product. , 2014, , .		15
64	Solder-glass attachment in Cerdip/Cerquad packages: thermally induced stresses and mechanical reliability. , 0, , .		14
65	Effect of rapid thermal annealing (RTA) on thermal properties of carbon nanofibre (CNF) arrays. Journal Physics D: Applied Physics, 2006, 39, 4878-4885.	1.3	14
66	Improved performances of polymer-based dielectric by using inorganic/organic core-shell nanoparticles. Applied Physics Letters, 2012, 101, .	1.5	14
67	Could application of column-grid-array (CGA) technology result in inelastic-strain-free state-of-stress in solder material?. Journal of Materials Science: Materials in Electronics, 2015, 26, 10062-10067.	1.1	14
68	Human-in-the-Loop. , 0, , .		14
69	Bonding strength of a carbon nanofiber array to its substrate. Journal of Materials Research, 2006, 21, 2922-2926.	1.2	13
70	Probabilistic Palmgrenâ€“Miner rule, with application to solder materials experiencing elastic deformations. Journal of Materials Science: Materials in Electronics, 2017, 28, 2680-2685.	1.1	13
71	Effective Young's modulus of carbon nanofiber array. Journal of Materials Research, 2006, 21, 2948-2954.	1.2	12
72	On a paradoxical situation related to lap shear joints: could transverse grooves in the adherends reduce the interfacial stresses?. Journal Physics D: Applied Physics, 2008, 41, 115505.	1.3	12

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73	When adequate and predictable reliability is imperative. Microelectronics Reliability, 2012, 52, 2342-2346.	0.9	12
74	Predicted Size of an Inelastic Zone in a Ball-Grid-Array Assembly. Journal of Applied Mechanics, Transactions ASME, 2013, 80, .	1.1	12
75	Statistics-related and reliability-physics-related failure processes in electronics devices and products. Modern Physics Letters B, 2014, 28, 1450105.	1.0	12
76	Predicted stresses in a ball-grid-array (BGA)/column-grid-array (CGA) assembly with a low modulus solder at its ends. Journal of Materials Science: Materials in Electronics, 2015, 26, 9680-9688.	1.1	12
77	Solder material experiencing low temperature inelastic stress and random vibration loading: predicted remaining useful lifetime. Journal of Materials Science: Materials in Electronics, 2017, 28, 3585-3597.	1.1	12
78	What could and should be done differently: failure-oriented-accelerated-testing (FOAT) and its role in making an aerospace electronics device into a product. Journal of Materials Science: Materials in Electronics, 2018, 29, 2939-2948.	1.1	12
79	Short note - assessment of the required human capacity factor using flight simulator as an appropriate accelerated test vehicle. International Journal of Human Factors Modelling and Simulation, 2019, 7, 71.	0.1	12
80	Short note - adequate trust, human-capacity-factor, probability-distribution-function of human non-failure and its entropy. International Journal of Human Factors Modelling and Simulation, 2019, 7, 75.	0.1	12
81	Linear and nonlinear vibrations caused by periodic impulses. , 1985, , .		11
82	Stresses in bi-material GaN assemblies. Journal of Applied Physics, 2011, 110, .	1.1	11
83	Design-for-reliability (DfR) of aerospace electronics: Attributes and challenges. , 2013, , .		11
84	Predicted Thermal Stresses in a Trimaterial Assembly With Application to Silicon-Based Photovoltaic Module. Journal of Applied Mechanics, Transactions ASME, 2013, 80, .	1.1	11
85	Human-in-the-Loop (HITL): Probabilistic Predictive Modeling (PPM) of an Aerospace Mission/Situation Outcome. Aerospace, 2014, 1, 101-136.	1.1	11
86	To Burn-In, or Not to Burn-In: Thatâ€™s the Question. Aerospace, 2019, 6, 29.	1.1	11
87	Interfacial stresses in a bi-material assembly with a compliant bonding layer. Journal Physics D: Applied Physics, 2008, 41, 115504.	1.3	10
88	Analysis of a Bow-Free Prestressed Test Specimen. Journal of Applied Mechanics, Transactions ASME, 2014, 81, .	1.1	10
89	Analytical bathtub curve with application to electron device reliability. Journal of Materials Science: Materials in Electronics, 2015, 26, 6633-6638.	1.1	10
90	Human-in-the-loop: probabilistic predictive modelling, its role, attributes, challenges and applications. Theoretical Issues in Ergonomics Science, 2015, 16, 99-123.	1.0	10

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91	Astronaut's performance vs. his/hers human-capacity-factor and state-of-health: Application of double-exponential-probability-distribution function. Acta Astronautica, 2021, 178, 250-256.	1.7	10
92	<title>Accelerated life testing (ALT) in microelectronics and photonics: its role, attributes, challenges, pitfalls, and interaction with qualification tests</title>. , 2002, 4703, 162.		9
93	Elastic Stability of a Cantilever Beam (Rod) Supported by an Elastic Foundation, With Application to Nano-Composites. Journal of Applied Mechanics, Transactions ASME, 2012, 79, .	1.1	9
94	Assuring Electronics Reliability: What Could and Should Be Done Differently. , 2013, , .		9
95	Probabilistic modelling of the concept of anticipation in aviation. Theoretical Issues in Ergonomics Science, 2015, 16, 69-85.	1.0	9
96	Static fatigue lifetime of optical fibers assessed using Boltzmannâ€“Arrheniusâ€“Zhurkov (BAZ) model. Journal of Materials Science: Materials in Electronics, 2017, 28, 11689-11694.	1.1	9
97	Human-in-the-loop: application of the double exponential probability distribution function enables one to quantify the role of the human factor. International Journal of Human Factors Modelling and Simulation, 2017, 5, 354.	0.1	9
98	Flip-Chip (FC) and Fine-Pitch-Ball-Grid-Array (FPBGA) Underfills for Application in Aerospace Electronicsâ€”Brief Review. Aerospace, 2018, 5, 74.	1.1	9
99	Analytical thermal stress modeling in electronics and photonics engineering: Application of the concept of interfacial compliance. Journal of Thermal Stresses, 2019, 42, 29-48.	1.1	9
100	Using yield to predict long-term reliability of integrated circuits: Application of Boltzmann-Arrhenius-Zhurkov model. Solid-State Electronics, 2020, 164, 107746.	0.8	9
101	Stress Relief in Solder Joints Due to the Application of a Flex Circuit. Journal of Electronic Packaging, Transactions of the ASME, 1991, 113, 240-243.	1.2	8
102	How Compliant Should a Die-Attachment be to Protect the Chip From Substrate Bowing?. Journal of Electronic Packaging, Transactions of the ASME, 1995, 117, 88-92.	1.2	8
103	Predicted thermal stresses in a bow-free adhesively bonded assembly for photonic packaging applications. Elektrotechnik Und Informationstechnik, 2003, 120, 195-199.	0.7	8
104	Elastic stability of a dual-coated optical fiber of finite length. Journal of Applied Physics, 2007, 102, 043107.	1.1	8
105	Predictive Modeling of the Dynamic Response of Electronic Systems to Shocks and Vibrations. Applied Mechanics Reviews, 2010, 63, .	4.5	8
106	Aerospace optoelectronics reliability: application of multi-parametric BAZ model. , 2014, , .		8
107	Column-grid-array (CGA) versus ball-grid-array (BGA): board-level drop test and the expected dynamic stress in the solder material. Journal of Materials Science: Materials in Electronics, 2016, 27, 11572-11582.	1.1	8
108	Predicted stresses in a ball-grid-array (BGA)/column-grid-array (CGA) assembly with an epoxy adhesive at its ends. Journal of Materials Science: Materials in Electronics, 2016, 27, 4399-4409.	1.1	8

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109	Expected stress relief in a bi-material inhomogeneously bonded assembly with a low-modulus-and/or-low-fabrication-temperature bonding material at the ends. Journal of Materials Science: Materials in Electronics, 2016, 27, 5563-5574.	1.1	8
110	Bi-material assembly with a low-modulus-and/or-low-fabrication-temperature bonding material at its ends: optimized stress relief. Journal of Materials Science: Materials in Electronics, 2016, 27, 4816-4825.	1.1	8
111	Predicted stresses in ball-grid-array (BGA) and column-grid-array (CGA) interconnections in a mirror-like package design. Journal of Materials Science: Materials in Electronics, 2016, 27, 2430-2441.	1.1	8
112	Towards Probabilistic Analysis of Human-System Integration in Automated Driving. Advances in Intelligent Systems and Computing, 2020, , 9-14.	0.5	8
113	Saint-Venantâ€™s principle and the minimum length of a dual-coated optical fiber specimen in reliability (proof) testing. Microelectronics Reliability, 2013, 53, 1506-1509.	0.9	7
114	Bi-material assembly subjected to thermal stress: propensity to delamination assessed using interfacial compliance model. Journal of Materials Science: Materials in Electronics, 2016, 27, 6779-6785.	1.1	7
115	Avoiding collision in automated driving situation. Theoretical Issues in Ergonomics Science, 2021, 22, 251-260.	1.0	7
116	Reliability improvement through nanoparticle material-based fiber structures. Optical Fiber Technology, 2007, 13, 27-31.	1.4	6
117	Compliance properties study of carbon nanofibres (CNFs) array as thermal interface material. Journal Physics D: Applied Physics, 2008, 41, 155105.	1.3	6
118	Disc-like copper vias fabricated in a silicon wafer: Design for reliability. , 2008, , .		6
119	Predicted Response of the Die-Carrier Assembly in Flexible Electronics to the Combined Action of Tension and Bending Applied to the Carrier. Journal of Applied Mechanics, Transactions ASME, 2012, 79, .	1.1	6
120	STRUCTURAL DYNAMICS OF ELECTRONIC SYSTEMS. Modern Physics Letters B, 2013, 27, 1330004.	1.0	6
121	Probabilistic design for reliability in electronics and photonics: Role, significance, attributes, challenges. , 2015, , .		6
122	Predicted Thermal- and Lattice-Mismatch Stresses. , 2015, , 983-1005.		6
123	Electron Device Subjected to Temperature Cycling: Predicted Time-to-Failure. Journal of Electronic Materials, 2019, 48, 778-779.	1.0	6
124	Fiber optics engineering: Physical design for reliability. Facta Universitatis - Series Electronics and Energetics, 2014, 27, 153-182.	0.6	6
125	Mechanical behavior and reliability of solder joint interconnections in thermally matched assemblies. , 0, , .		5
126	Elastic stability of a dual coated optical fiber with a stripped off coating at its end. Journal of Applied Physics, 2007, 102, .	1.1	5

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127	Response of a heavy electronic component to harmonic excitations applied to its external electric leads. Elektrotechnik Und Informationstechnik, 2007, 124, 309-314.	0.7	5
128	Interfacial Stresses in a Lap Shear Joint (LSJ): The "Transverse Groove Effect" (TGE). Journal of Solid Mechanics and Materials Engineering, 2010, 4, 1116-1130.	0.5	5
129	Duffing Oscillator: Could an Impact Load of Finite Duration be Substituted with an Instantaneous Impulse?. Journal of Solid Mechanics and Materials Engineering, 2010, 4, 1381-1397.	0.5	5
130	Probabilistic modelling of the role of the human factor in the Helicopter-Landing-Ship (HLS) situation. International Journal of Human Factors Modelling and Simulation, 2010, 1, 313.	0.1	5
131	Predicted stresses in die-carrier assemblies in â€œstretchableâ€•electronics: is there an incentive for using a compliant bond?. ZAMM Zeitschrift Fur Angewandte Mathematik Und Mechanik, 2011, 91, 57-67.	0.9	5
132	Quantified Reliability of Aerospace Optoelectronics. SAE International Journal of Aerospace, 2014, 7, 65-73.	4.0	5
133	Reliability physics and probabilistic design for reliability (PDfR): Role, attributes, challenges. , 2014, , .		5
134	Analytical (mathematical) predictive modeling in fiber optics structural analysis (FOSA): review and extension. Proceedings of SPIE, 2015, , .	0.8	5
135	Analytical thermal stress model for a typical flip-chip (FC) package design. Journal of Materials Science: Materials in Electronics, 2018, 29, 2676-2688.	1.1	5
136	Head-on railway obstruction: a probabilistic model. Theoretical Issues in Ergonomics Science, 2020, , 1-7.	1.0	5
137	Probabilistic approach to evaluate improvements in the reliability of a chip-substrate (chip-card) assembly. IEEE Transactions on Components and Packaging Technologies, 1997, 20, 60-63.	0.7	4
138	The future of microelectronics and photonics and the role of mechanics and materials. , 0, , .		4
139	Semiconductor film grown on a circular substrate: predictive modeling of lattice-misfit stresses. Journal of Materials Science: Materials in Electronics, 2016, 27, 9356-9362.	1.1	4
140	Aerospace Mission Outcome: Predictive Modeling. Aerospace, 2018, 5, 56.	1.1	4
141	Probabilistic reliability-physics models in aerospace human-in-the-loop (HITL) problems. , 2019, , 499-516.		4
142	Survivability of species in different habitats: Application of multi-parametric Boltzmann-Arrhenius-Zhurkov equation. Acta Astronautica, 2020, 175, 249-253.	1.7	4
143	Predictive modeling sheds useful light on burn-in testing (BIT): Brief review and recent extension. Microelectronics Reliability, 2022, 128, 114371.	0.9	4
144	Microelectronics and photonics-the future. , 0, , .		3

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145	Analysis of an elongated stretched strip, with application to a strain-gage electrical sensor design. ZAMM Zeitschrift Fur Angewandte Mathematik Und Mechanik, 2011, 91, 330-338.	0.9	3
146	Scanning acoustic microscopy and shear wave imaging mode performances for failure detection in high-density microassembling technologies. , 2015, , .		3
147	Aging-related failure rate obtained from bathtub curve data. , 2015, , .		3
148	Could dynamic strength of a bonding material in an electronic device be assessed from static shear-off test data?. Journal of Materials Science: Materials in Electronics, 2016, 27, 6697-6702.	1.1	3
149	Board level drop test: exact solution to the problem of the nonlinear dynamic response of a PCB to the drop impact. Journal of Materials Science: Materials in Electronics, 2016, 27, 9423-9430.	1.1	3
150	How Many Peripheral Solder Joints in a Surface Mounted Design Experience Inelastic Strains?. Journal of Electronic Materials, 2017, 46, 1747-1753.	1.0	3
151	Quantifying the roles of human error and his/her state-of-health: use of the double-exponential-probability-distribution-function. International Journal of Human Factors Modelling and Simulation, 2018, 6, 140.	0.1	3
152	Degraded situation awareness risk assessment in the aerospace domain. , 2019, , .		3
153	Some Major Human Issues in Aerospace Engineering: Review and Extension. Lecture Notes in Networks and Systems, 2021, , 169-177.	0.5	3
154	Short note - assessment of the required human capacity factor using flight simulator as an appropriate accelerated test vehicle. International Journal of Human Factors Modelling and Simulation, 2019, 7, 71.	0.1	3
155	Short note - adequate trust, human-capacity-factor, probability-distribution-function of human non-failure and its entropy. International Journal of Human Factors Modelling and Simulation, 2019, 7, 75.	0.1	3
156	Analytical (“mathematical”) modeling of the dynamic response of a printed circuit board (PCB) to an impact load. , 2010, , .		2
157	Predicted size of the inelastic zone in a ball-grid-array (BGA) assembly. , 2013, , .		2
158	Thermomechanical stress analysis of copper/silicon interface in through silicon vias using FEM simulations and experimental analysis. , 2014, , .		2
159	A novel approach for evaluation of material interfaces in electronics. , 2016, , .		2
160	Dynamic response of electronic materials to impact loading: review. ZAMM Zeitschrift Fur Angewandte Mathematik Und Mechanik, 2017, 97, 699-717.	0.9	2
161	Assessed interfacial strength and elastic moduli of the bonding material from shear-off test data. Journal of Materials Science: Materials in Electronics, 2017, 28, 6794-6799.	1.1	2
162	Flip-chip assembly: is the bi-material model acceptable?. Journal of Materials Science: Materials in Electronics, 2017, 28, 15775-15781.	1.1	2

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163	Physical Design for Reliability of Solder Joint Interconnections for Application in Aerospace Electronics. , 2019, , .		2
164	When Instrumentation and Human Performance Contribute Jointly to the Outcome of a Human-System-Integration (HSI) Mission: Brief Review. Lecture Notes in Networks and Systems, 2021, , 409-413.	0.5	2
165	Driver propensity to fatigue and drowsiness: a probabilistic approach. Theoretical Issues in Ergonomics Science, 0, , 1-17.	1.0	2
166	Figure-of-Merit for a Long-Term Survivorship of a Species Determined from the Short-Term Mortality Rate of Its Individual Organisms. Biophysical Reviews and Letters, 2021, 16, 111-123.	0.9	2
167	Quantifying the roles of human error and his/her state-of-health: use of the double-exponential-probability-distribution-function. International Journal of Human Factors Modelling and Simulation, 2018, 6, 140.	0.1	2
168	Design for ReliabilityÂof Electronic Materials and Systems. , 2019, , 1-10.		2
169	Quantifying surgeonâ€™s performance: probabilistic approach. British Journal of Surgery, 2022, , .	0.1	2
170	Fiber optic interconnects: physical design for reliability. , 2010, , .		1
171	Physical Properties and Mechanical Behavior of Carbon Nano-tubes (CNTs) and Carbon Nano-fibers (CNFs) as Thermal Interface Materials (TIMs) for High-Power Integrated Circuit (IC) Packages: Review and Extension. , 2010, , 315-347.		1
172	Dynamic response of electronic systems to shocks and vibrations: Application of analytical (mathematical) modeling. EPJ Web of Conferences, 2012, 26, 05002.	0.1	1
173	Bending of a bi-material cantilever beam, with consideration of the role of the interfacial shearing stress. ZAMM Zeitschrift Fur Angewandte Mathematik Und Mechanik, 2012, 92, 573-582.	0.9	1
174	Towards adequate qualification testing of electronic products: Review and extension. , 2014, , .		1
175	Bow-Free Tri-Component Mechanically Pre-Stressed Failure-Oriented-Accelerated-Test (FOAT) Specimen. , 2015, , .		1
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